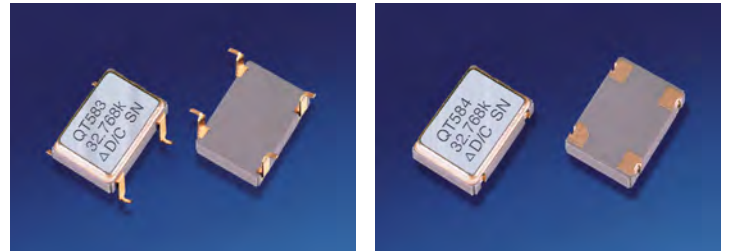
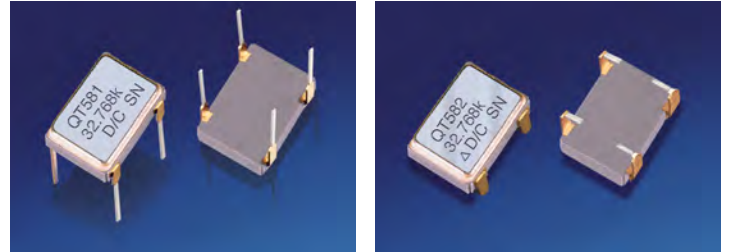


Description

Q-Tech's high temperature real time clock oscillators consist of a source clock square wave generator and a miniature round or strip quartz crystal built in a low profile hermetically ceramic package with gold plated contact terminals.

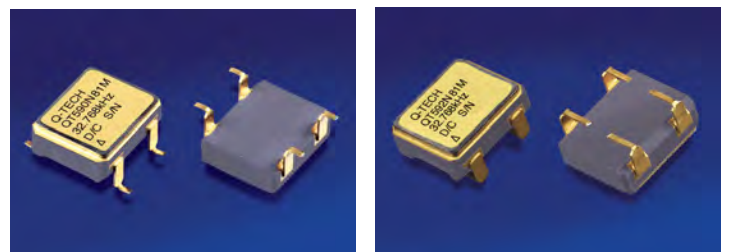
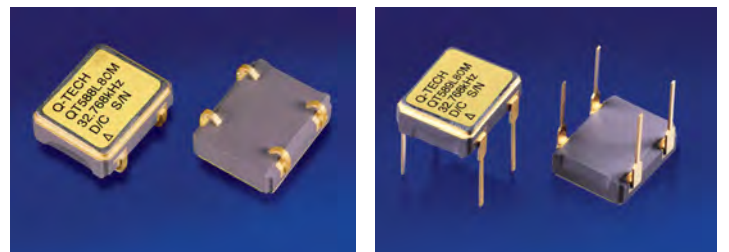
The device provides a precision clock for timekeeping for most down-hole electronic applications by using AT on cut quartz crystals. The design and construction of the QT581 and QT588 series will make accuracy-improvement techniques over the traditional RTC with a 32.768kHz quartz tuning-fork crystal, which due to its parabolic characteristics that do not provide much accuracy over a wide temperature range. As a result, there is a gaining or losing up to seconds per day and tens of minutes per year.

The device is built using high temperature materials and processes suitable for long life and highest reliability.



Features

- Made in the USA
- ECCN: EAR99
- +3.3Vdc and +2.5Vdc operation
- 32.768kHz square wave CMOS output
- Wide operating temperature -55°C to +200°C
- Tight frequency stability ($\pm 40\text{ppm}$ to $\pm 250\text{ppm}$)
- Ultra-low current suitable for battery operation
- Excellent AT and IT cut crystal temperature characteristics
- Tristate output standard
- Fundamental design
- Fast start-up time
- Hermetically sealed package
- 100% testing over temperature



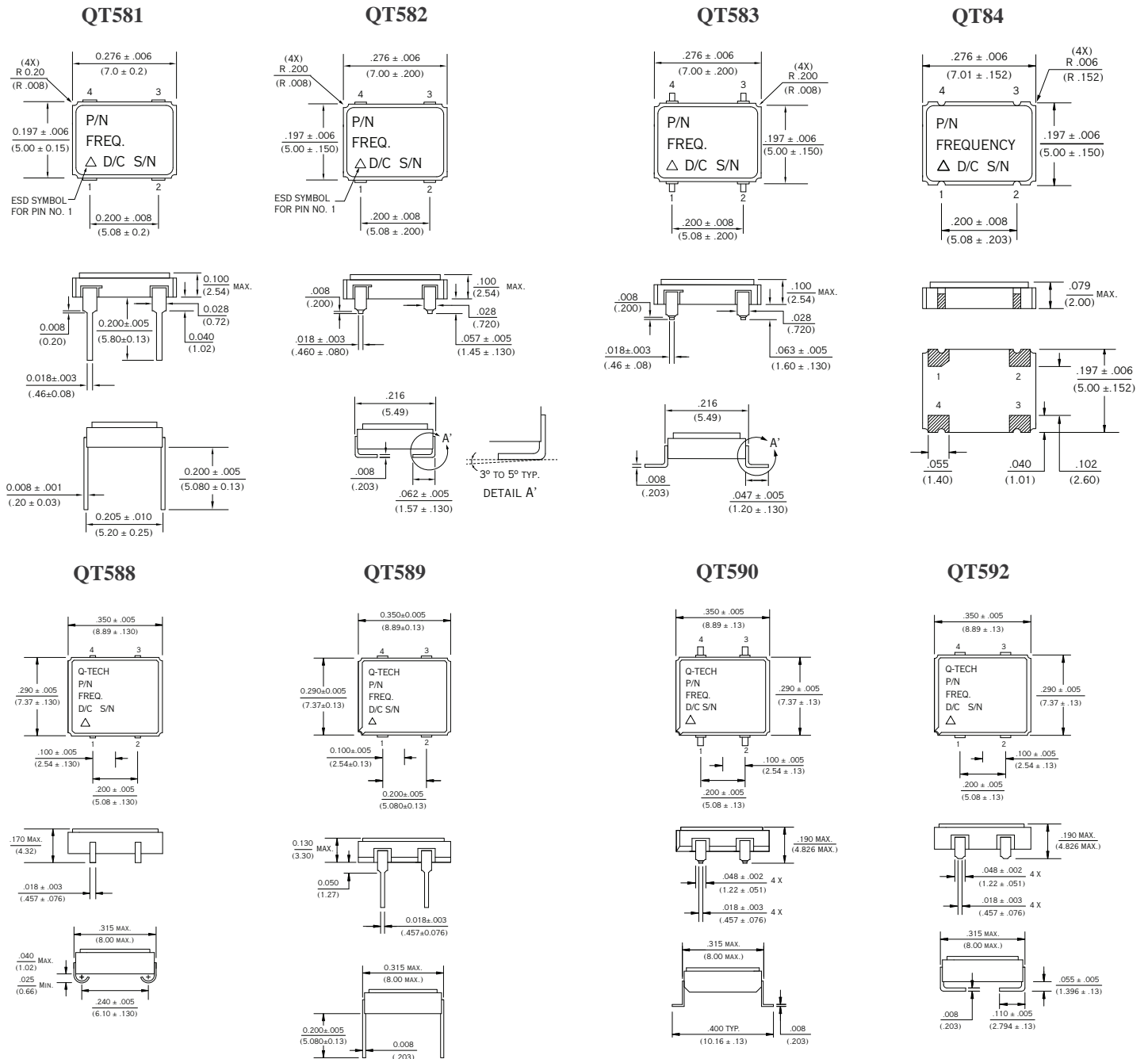
Applications

- Real-time clock driver
- 32.768kHz output crystal modules

Electrical Characteristics

Parameters	+3.3Vdc	+2.5Vdc
Output frequency (Fo)	32.768kHz	
Supply voltage (Vdd)	+3.3Vdc \pm 10%	+2.5Vdc \pm 10%
Maximum Applied Voltage (Vdd max.)	+5Vdc	
Frequency stability ($\Delta F/\Delta T$)	See Ordering Information	
Operating temperature (Topr)	See Ordering Information	
Storage temperature (Tsto)	-55°C to + 125°C	
Operating supply current (Idd) (No Load)	0.42 mA typ., 0.7mA max.	0.24 mA typ., 0.5mA max.
Symmetry (50% of ouput waveform)	50/50% typ., 45/55% max.	
Rise and Fall times (Tr, Tf between 10% and 90% of output waveform)	0.2 μ s typ., 1 μ s max.	
Output Load	15pF	
Start-up time (Tstup)	10ms max.	
Output voltage (Voh/Vol)	0.9 x Vdd min.; 0.1 x Vdd max.	
Output Current (Ioh/Iol)	\pm 2mA min.	
Enable/Disable function Pin 1	VIH \geq 0.7Vdd: Active VIL \leq 0.3Vdd: High Impedance Stand-by current: 10 μ A max.	
Aging	\pm 5ppm max. first year / \pm 2ppm max. per year thereafter	

Package Outline and Pin Connections - Dimensions are in inches (mm)

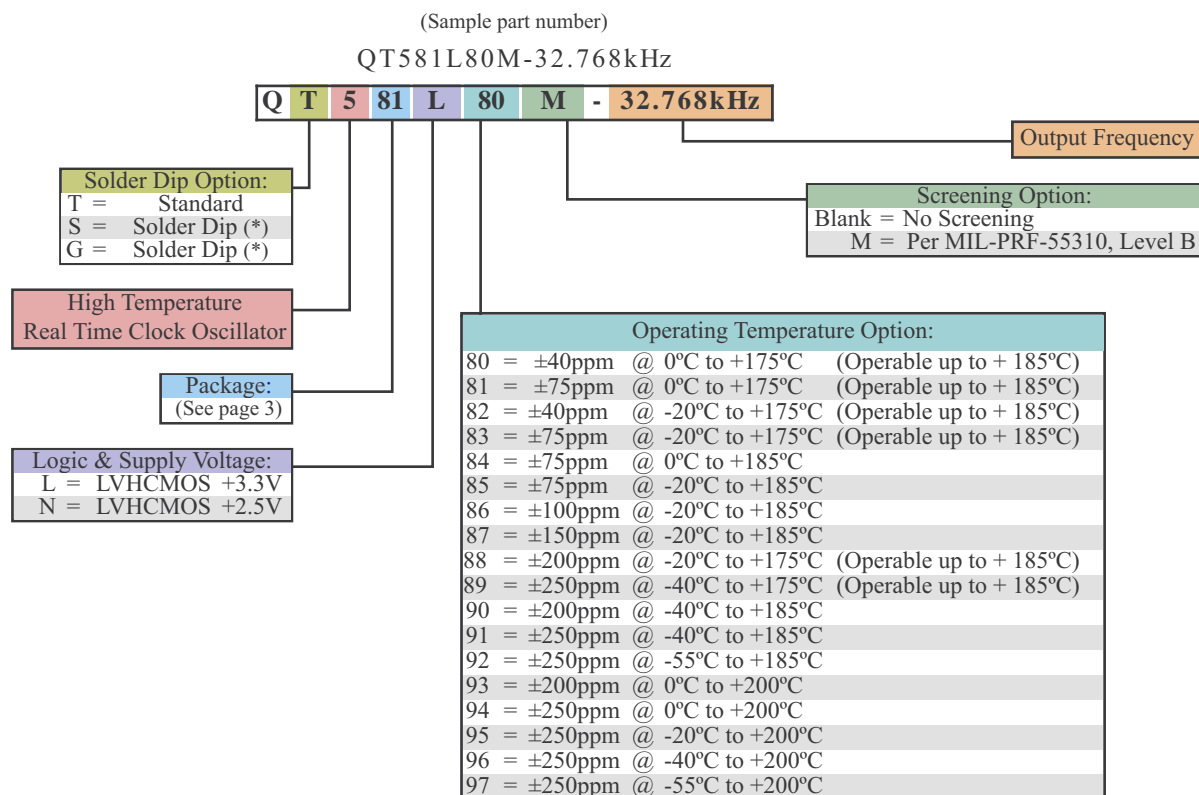


Package Information

- Package material: 91% AL₂O₃
- Lead material: Kovar
- Lead finish: Gold Plated: 50μ ~ 80μ inches
Nickel Underplate: 100μ ~ 250μ inches
- Weight: 0.6g typ., 3.0g max.

Pin No.	Function
1	TRISTATE
2	GND/CASE
3	OUTPUT
4	VDD

Ordering Information



For Non-Standard requirements, contact Q-Tech Corporation at Sales@Q-Tech.com

Packaging Options

- Standard packaging in black foam
- Standard packaging in anti-static plastic tube (60 pcs/tube)
- Tape and Reel (800 pcs/reel) is available for an additional charge.

Other Options Available For An Additional Charge

- P. I. N. D. test (MIL-STD 883, Method 2020, Condition B)

(*) Hot Solder Dip options for an additional cost:

S = Sn60/Pb40 per MIL-PRF 55310

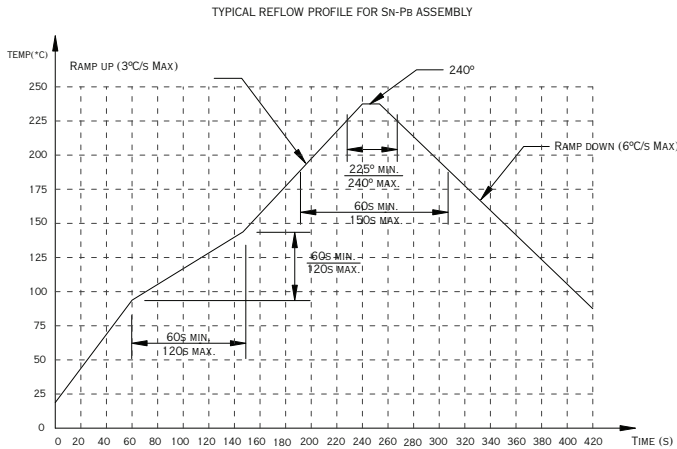
G = Lead free Alloy SAC305 (96.5% Sn, 3% Ag, 0.5% Cu)

Specifications subject to change without prior notice.

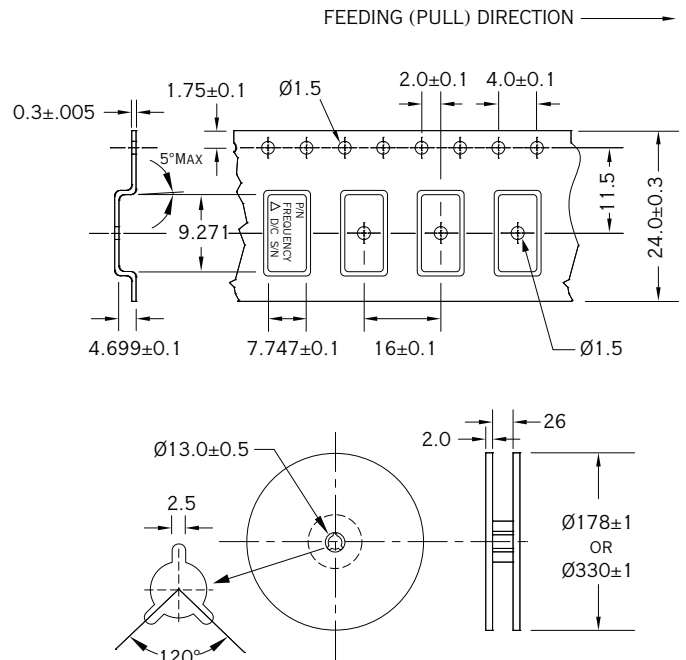
Reflow Profile

The five transition periods for the typical reflow process are:

- Preheat
- Flux activation
- Thermal equalization
- Reflow
- Cool down



Embossed Tape and Reel Information For QT588



Dimensions are in mm. Tape is compliant to EIA-481-A.

Reel size vs. quantity:

Reel size (Diameter in mm)	Qty per reel (pcs)
178	150
330	800

Environmental Specifications

Q-Tech Standard Screening/QCI (MIL-PRF55310) is available for all of our QT581 and QT588 series. Q-Tech can also customize screening and test procedures to meet your specific requirements. The QT581 and QT588 series are designed and processed to exceed the following test conditions:

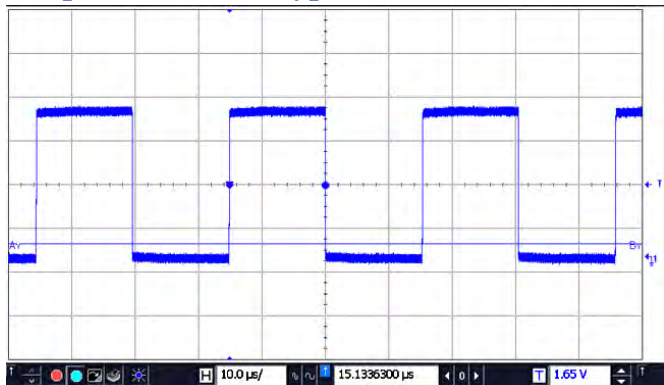
Environmental Test	Test Conditions
Temperature cycling	MIL-STD-883, Method 1010, Cond. B
Constant acceleration	MIL-STD-883, Method 2001, Cond. A, Y1
Seal: Fine and Gross Leak	MIL-STD-883, Method 1014, Cond. A and C
Burn-in	160 hours, 125°C with load
Aging	30 days, 70°C, ±1.5ppm max
Vibration sinusoidal	MIL-STD-202, Method 204, Cond. D
Shock, non operating	MIL-STD-202, Method 213, Cond. I (See Note 1)
Thermal shock, non operating	MIL-STD-202, Method 107, Cond. B
Ambient pressure, non operating	MIL-STD-202, 105, Cond. C, 5 minutes dwell time minimum
Resistance to solder heat	MIL-STD-202, Method 210, Cond. B
Moisture resistance	MIL-STD-202, Method 106
Terminal strength	MIL-STD-202, Method 211, Cond. C
Resistance to solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-202, Method 208
ESD Classification	MIL-STD-883, Method 3015, Class 1 HBM 0 to 1,999V
Moisture Sensitivity Level	J-STD-020, MSL=1

Note 1: Additional shock results successfully passed on 16MHz, 20MHz, 24MHz, 40MHz, and 80MHz

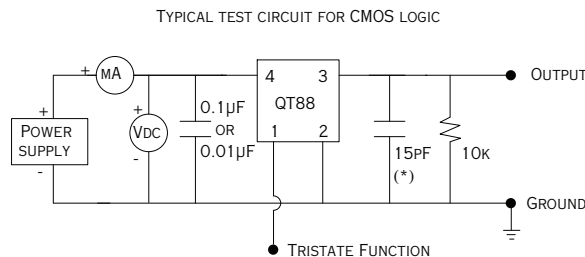
- Shock 850g peak, half-sine, 1 ms duration (MIL-STD-202, Method 213, Cond. D modified)
- Shock 1,500g peak, half-sine, 0.5ms duration (MIL-STD-883, Method 2002, Cond. B)
- Shock 36,000g peak, half-sine, 0.12 ms duration

Please contact Q-Tech for higher shock requirements

Output Waveform (Typical)



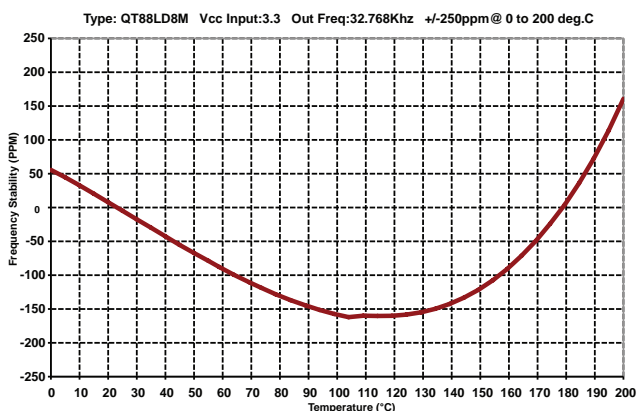
Test Circuit



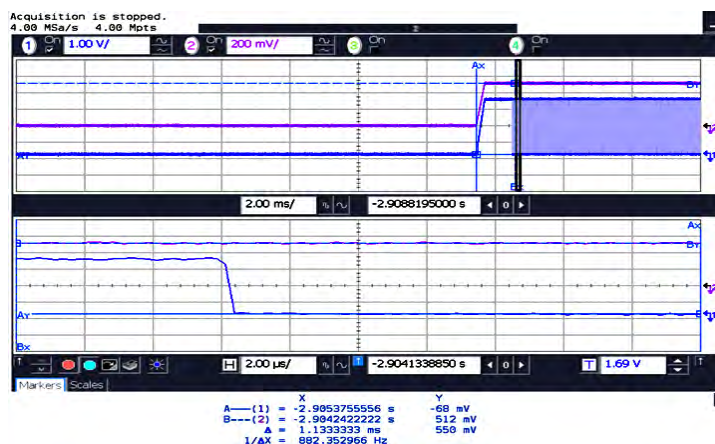
(* CL INCLUDES PROBE AND JIG CAPACITANCE

The Trisate function on pin 1 has a built-in pull-up resistor typical 50kΩ, so it can be left floating or tied to Vdd without deteriorating the electrical performance.

Frequency vs. Temperature Curve



Start up Time at 200°C



Thermal Characteristics

The heat transfer model in a hybrid package is described in figure 1.

Heat spreading occurs when heat flows into a material layer of increased cross-sectional area. It is adequate to assume that spreading occurs at a 45° angle.

The total thermal resistance is calculated by summing the thermal resistances of each material in the thermal path between the device and hybrid case.

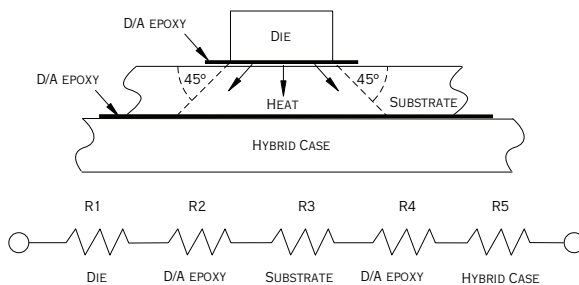
$$RT = R1 + R2 + R3 + R4 + R5$$

The total thermal resistance R_T (see figure 2) between the heat source (die) to the hybrid case is the Theta Junction to Case (Theta J_C) in °C/W.

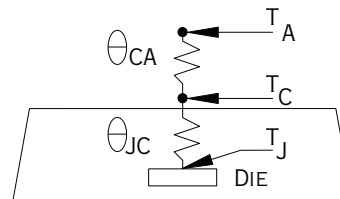
- Theta junction to case (Theta J_C) for this product is 30°C/W.
- Theta case to ambient (Theta C_A) for this part is 100°C/W.
- Theta Junction to ambient (Theta J_A) is 130°C/W.

Maximum power dissipation P_D for this package at 25°C is:

- $P_D(\max) = (T_J(\max) - T_A) / \text{Theta } J_A$
- With $T_J = 175^\circ\text{C}$ (Maximum junction temperature of die)
- $P_D(\max) = (175 - 25) / 130 = 1.15\text{W}$



(Figure 1)



$$\Theta_{JA} = \Theta_{JC} + \Theta_{CA}$$

(Figure 2)



Revision History

ECO	REV	REVISION SUMMARY	Page
10336	A	Added dimension tolerance to QT582 & QT583 outlines	3
		Added Solder Dip option G	3
		Modified ordering information table	4
		Added "Revision History" table	7
		Add document number on footer of all pages	All
11537	B	Updated Operating Temperature Options Table	4